

# Microstructure and microwave properties of low temperature sintered BST ( $\text{Ba}_{0.6}\text{Sr}_{0.4}\text{TiO}_3$ ) thick-films and their applicability to co-firing processes

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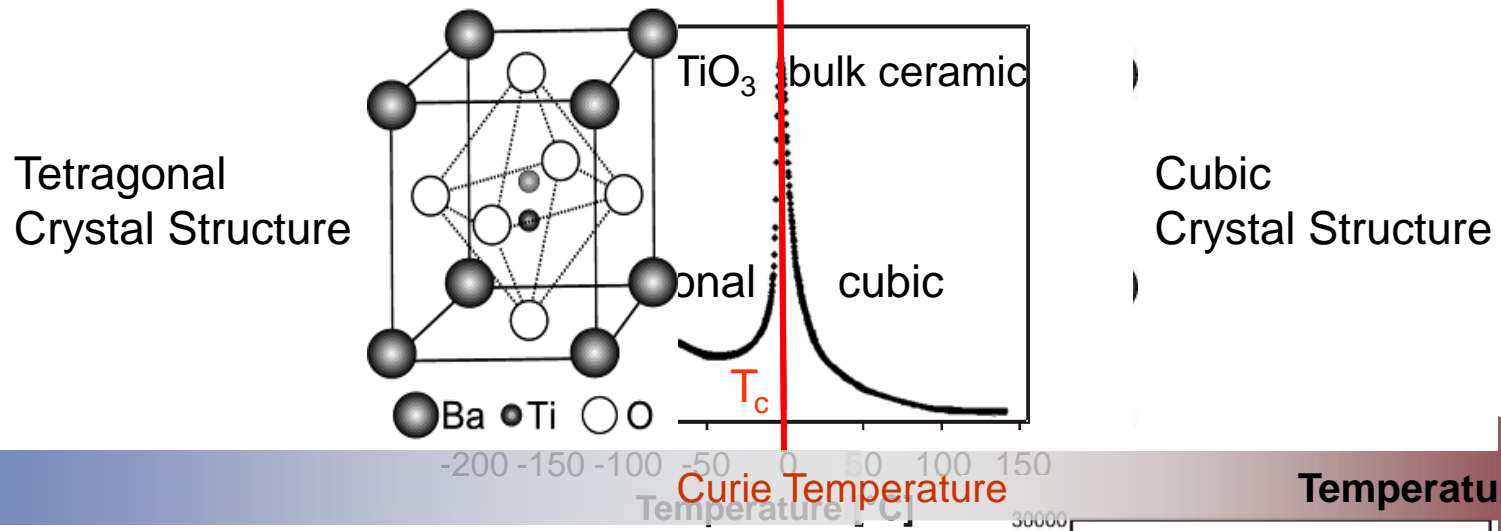
# Outline

- **Introduction**
  - $\text{Ba}_{1-x}\text{Sr}_x\text{TiO}_3$
  - Microwave components
- **Low temperature sintered BST thick-films**
  - Experimental route
  - Additive system
  - Microstructure and phase content
- **Dielectric characterisation**
  - Co-Firing of MIM structures
  - CPW vs. MIM
- **Summary and Outlook**

# System $Ba_{1-x}Sr_xTiO_3$ (BST)

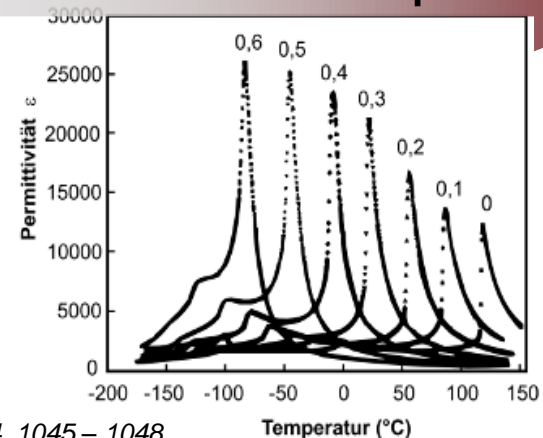
Ferroelectric Phase

Paraelectric Phase



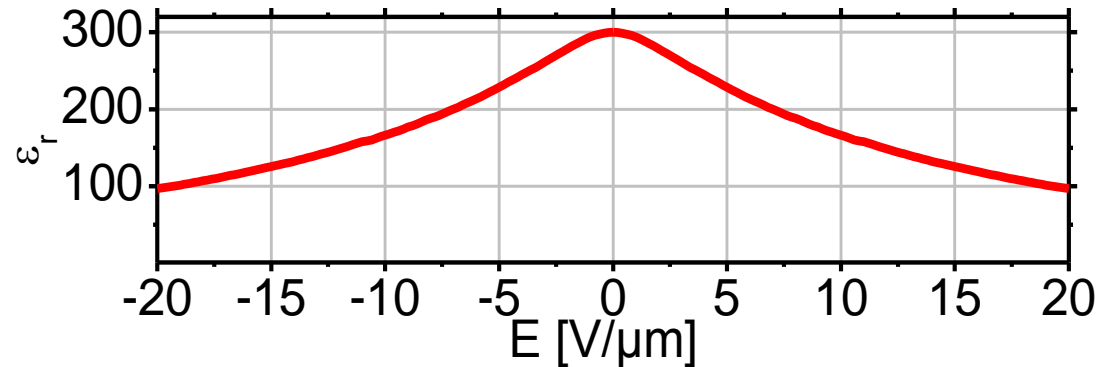
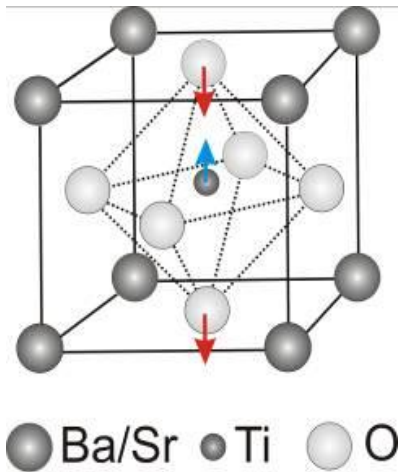
For microwave applications:

- usage of paraelectric phase
- application at RT  $\rightarrow Ba_{0.6}Sr_{0.4}TiO_3$



Jeon, J., *J. Eur. Ceram. Soc.*, 2004, 24, 1045 – 1048

# Ba<sub>0.6</sub>Sr<sub>0.4</sub>TiO<sub>3</sub> as tuneable dielectric material



BST shows a non-linear dependency of the permittivity on a static E-field

## Displacement of Ti<sup>4+</sup>-ion through an external electric field

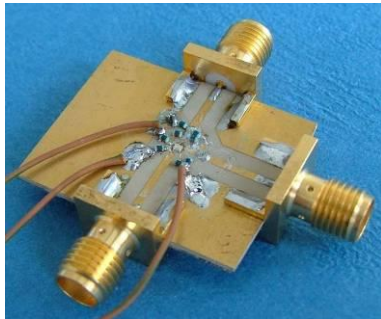
- *no power consumption*
- *high linearity*
- *fast tuning speed*

### Dielectric tunability

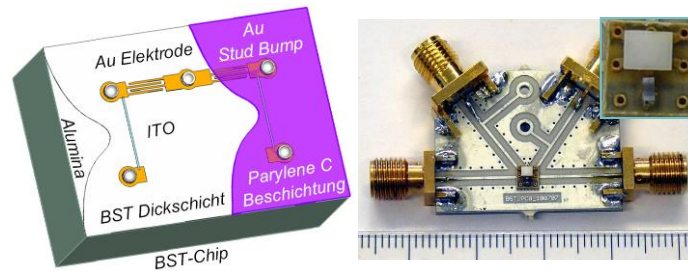
$$\tau_{\varepsilon}(\mathbf{E}) = \frac{\varepsilon_r(\mathbf{E}=0) - \varepsilon_r(\mathbf{E})}{\varepsilon_r(\mathbf{E}=0)}$$

# Microwave components based on BST thick-films

## Tunable filter

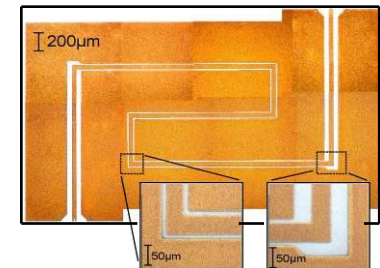


## Tunable matching network



## Phase shifter

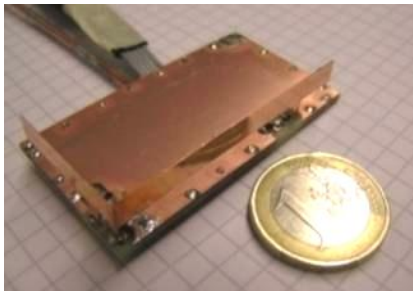
### CPW based phase shifter



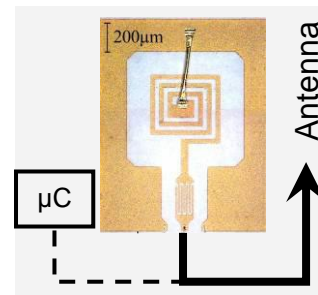
### Left-handed phase shifter



## Multiband antenna



## RF-ID modulator



Microwave Engineering, Technical University Darmstadt

<http://www.mwe.tu-darmstadt.de/de/fachgebiete/mikrowellentechnik/forschung/ferroelectrics/ferroelectrics.html>

# Motivation

## Restriction: High sintering temperature of BST thick film (~1200°C)

- co-firing with silver/gold electrodes not possible (melting point of silver = 962°C)
- co-fired MIM devices only feasible by using high temperature fireable electrodes (e.g. Pt)
- not compatible with LTCC technology (firing range 865-900°C)

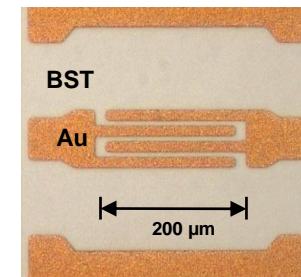
## BST varactors

- so far: fabrication of electrodes **after** firing of BST thick-films via fotolithography
- coplanar varactors (IDC, CPW)

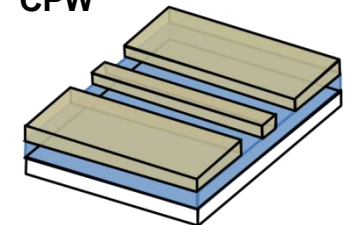
## Objectives

- development of low-temperature sintered BST-thick films
- fabrication of co-fired MIM devices

IDC

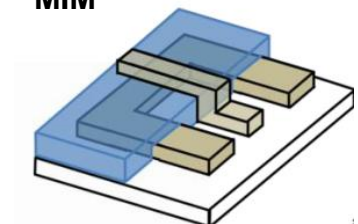


CPW

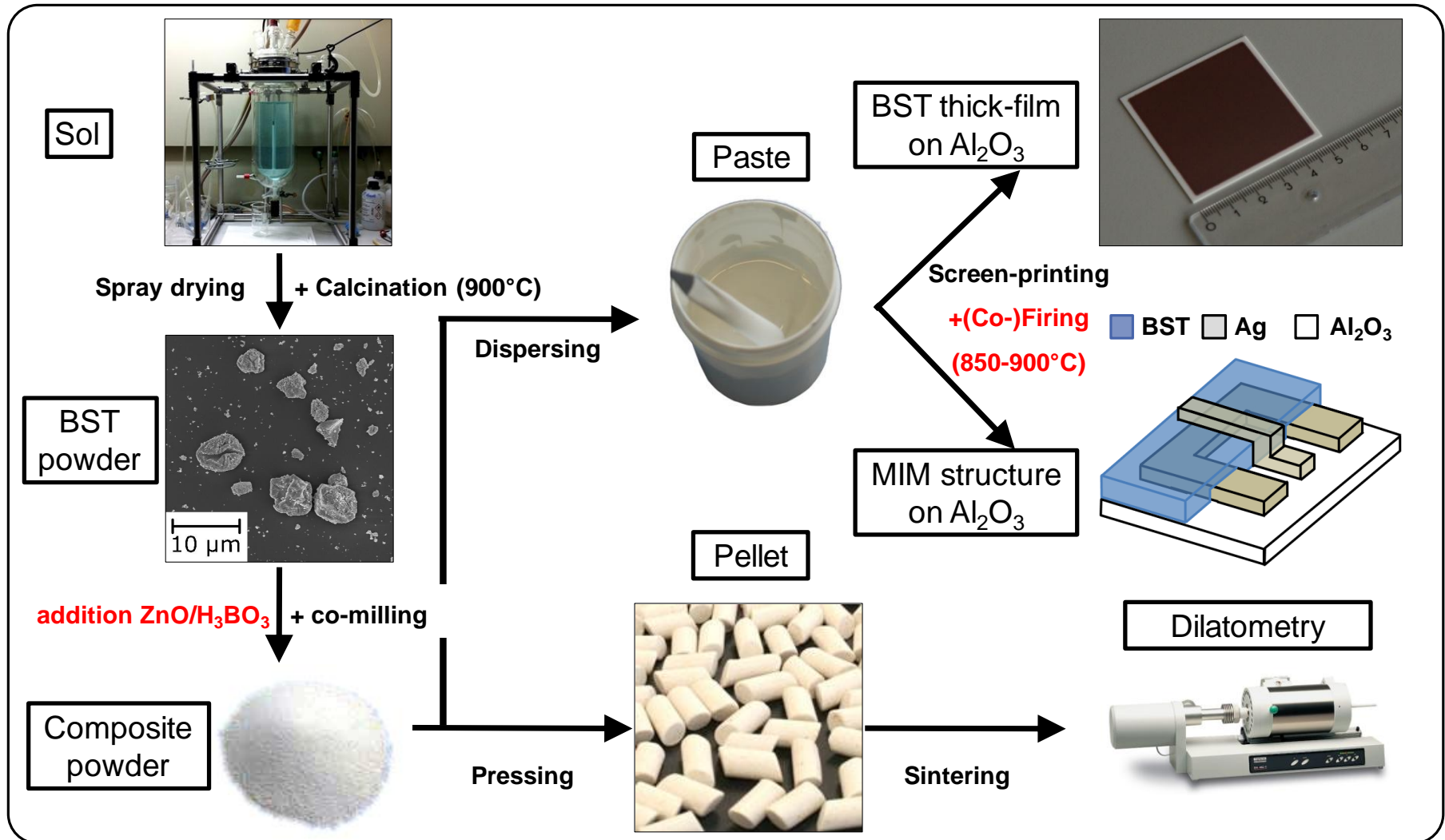


■ BST □ Ag □ Al<sub>2</sub>O<sub>3</sub>

MIM



# Experimental route



# Choice of additive system

## Requirement additive system

- lowering of sintering temperature of BST
- no or limited formation of secondary phases
- low permittivity and dielectric loss

→ ZnO-B<sub>2</sub>O<sub>3</sub> (molar ratio 1:1)

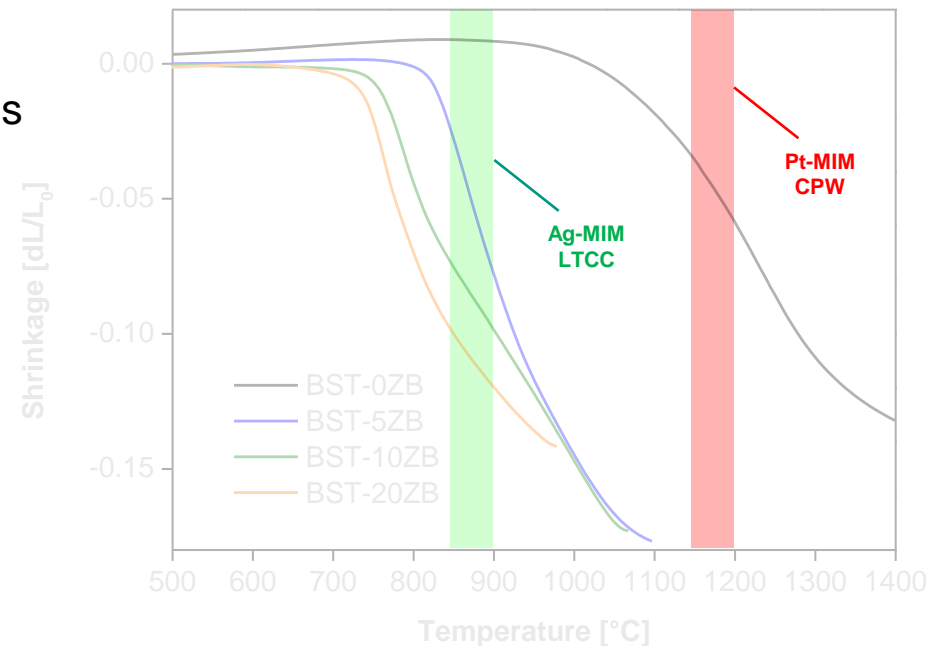
( $\epsilon_r = 6.9$ ,  $\tan \delta = 9.4 \times 10^{-3}$  (16 GHz), Surendran 2004)

→ mixing with BST via co-milling

## Samples

- 1.) **BST-5ZB** (5 vol.% ZnO-H<sub>3</sub>BO<sub>3</sub>)
- 2.) **BST-10ZB** (10 vol.% additive)
- 3.) **BST-20ZB** (20 vol.% additive)

## Dilatometry



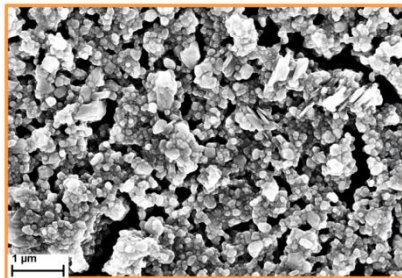
→ Reducing of sintering temperature

(further details: Kohler et al., IJAC 2013, doi: 10.1111/ijac.12116)

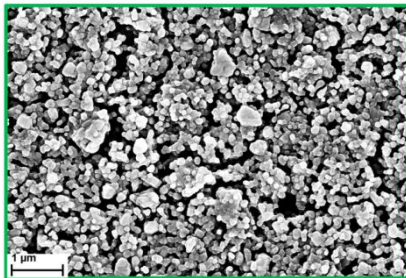


# Microstructure & phase content of thick films

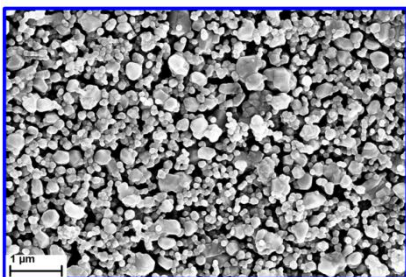
BST-20ZB (Porosity P = 34.8%)



BST-10ZB (P = 41.5%)



BST-5ZB (P = 45.0%)

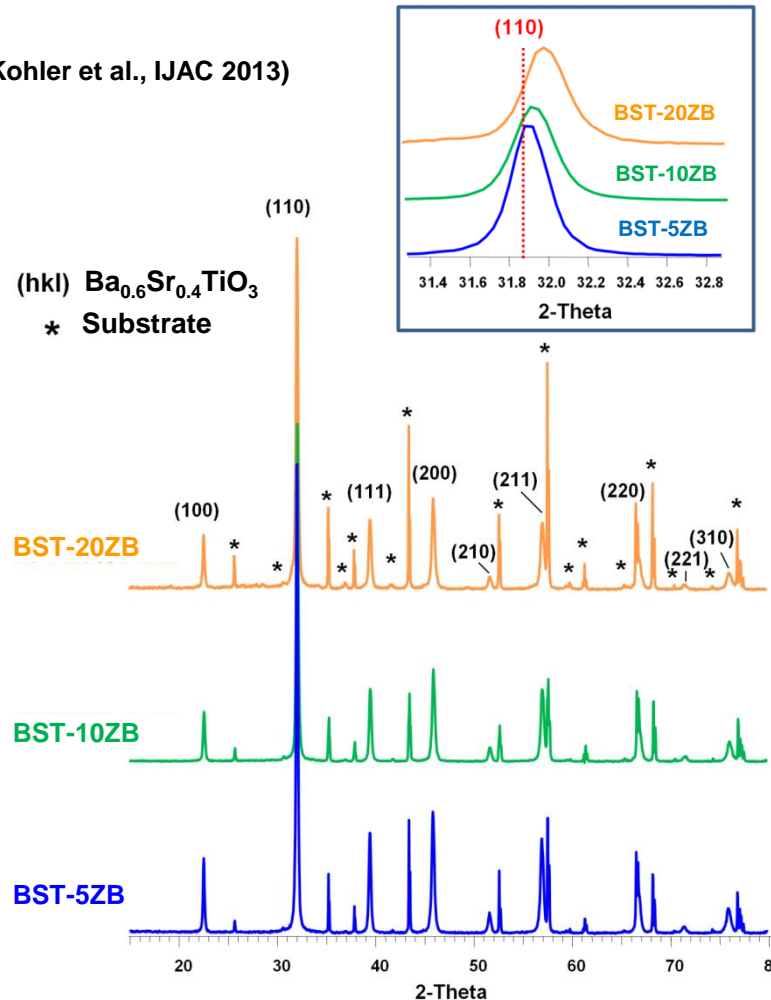


Higher additive amount

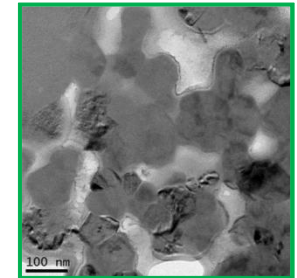
- lower grain sizes
- clustering of particles

(Kohler et al., IJAC 2013)

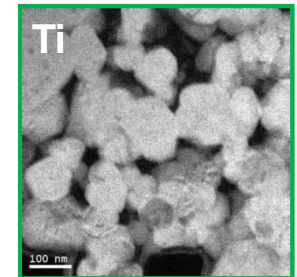
(hkl)  $Ba_{0.6}Sr_{0.4}TiO_3$   
\* Substrate



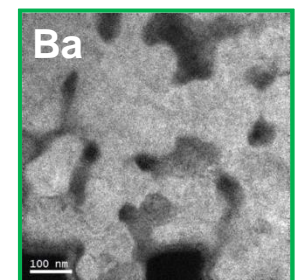
TEM BST-10ZB



Distribution Titanium



Distribution Barium

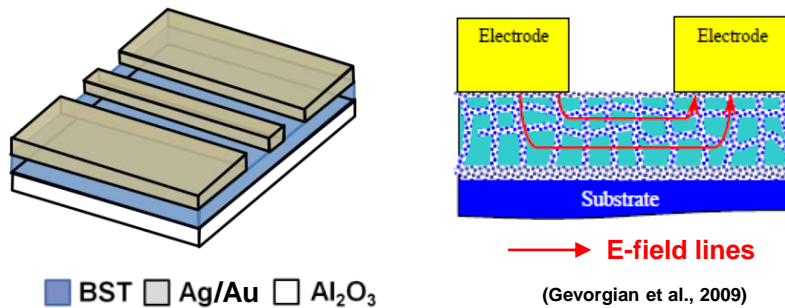


- no significant formation of (crystalline) secondary phases
- shift of BST main (110) reflex ( $Ba_{0.6}Sr_{0.4}TiO_3 \rightarrow Ba_{0.5}Sr_{0.5}TiO_3$ )

- dissolution of barium in amorphous phase

# Dielectric characterization – CPW vs. MIM

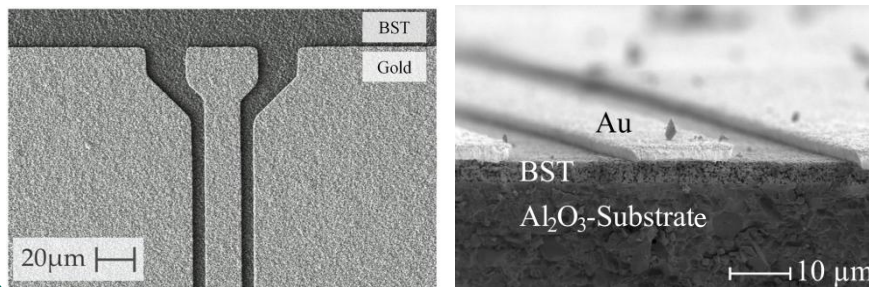
## Concept coplanar waveguides (CPW)



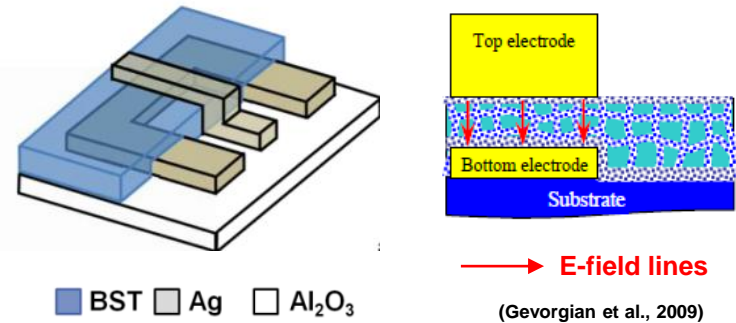
### Fabrication

1. Screen-printing BST-ZB paste on Al<sub>2</sub>O<sub>3</sub>
2. Drying and firing (**900°C/1h**) of thick-films
3. Fotolithography of gold electrodes

### Realized Structures



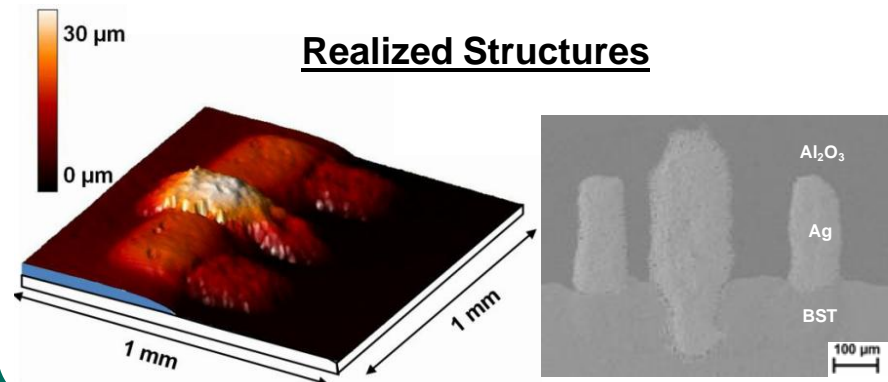
## Concept Metal-Insulator-Metal (MIM) structure



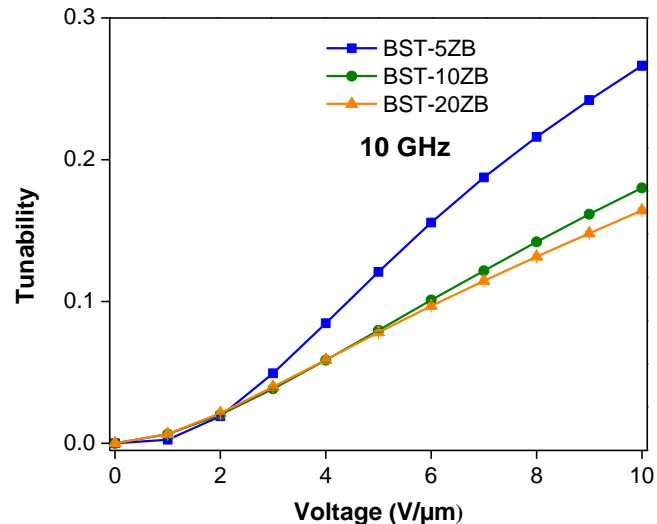
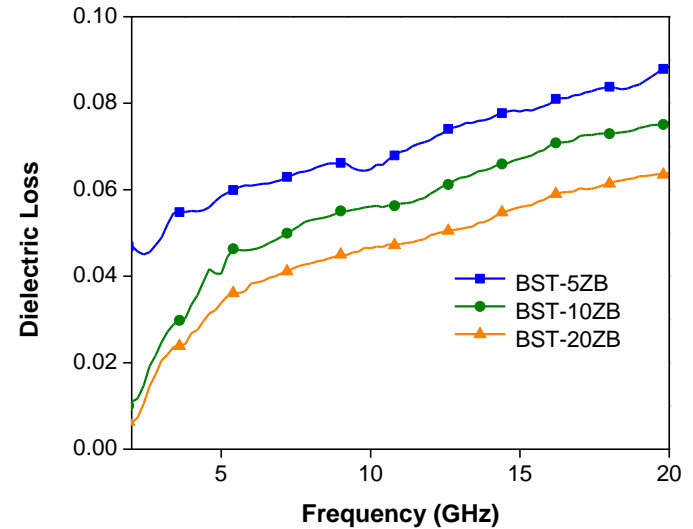
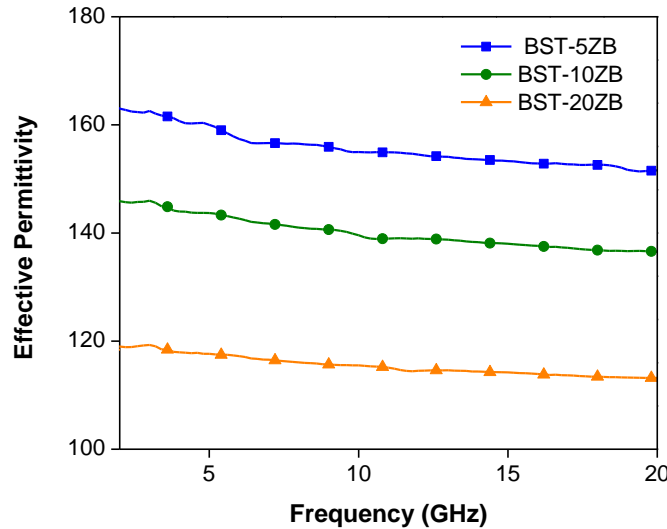
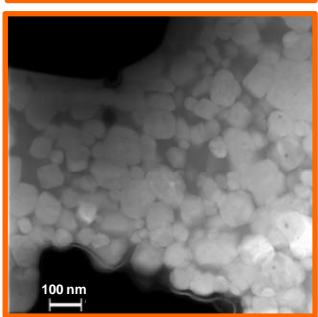
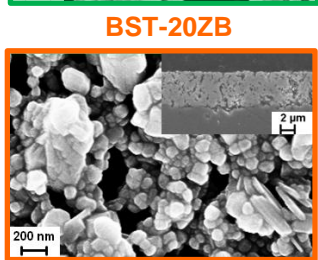
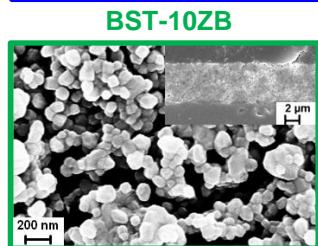
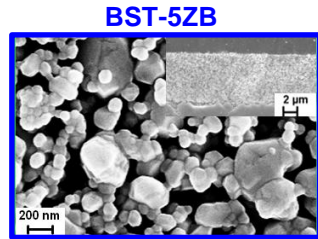
### Fabrication

1. Screen-printing of silver electrodes as well as BST-ZB pastes
2. Drying and **co-firing (865°C/1h)** of multilayer

### Realized Structures



# Dielectric characterization - CPW

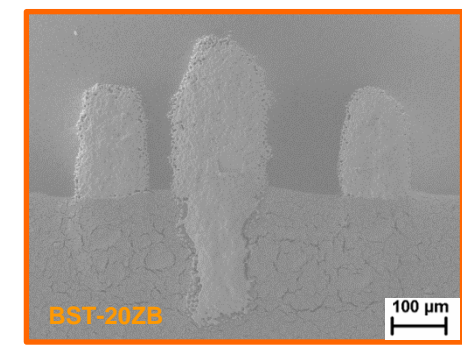
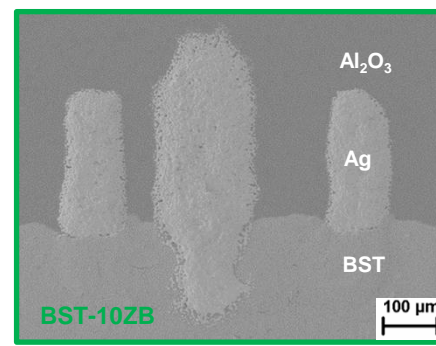
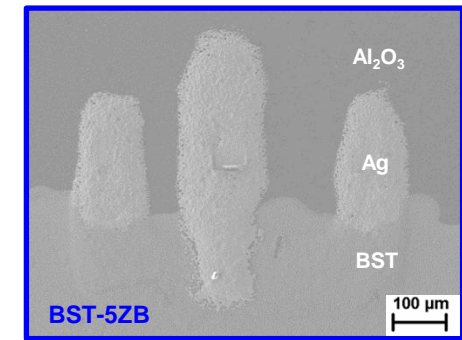
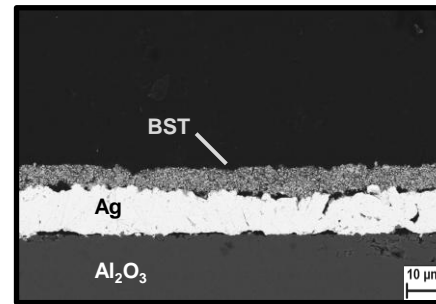
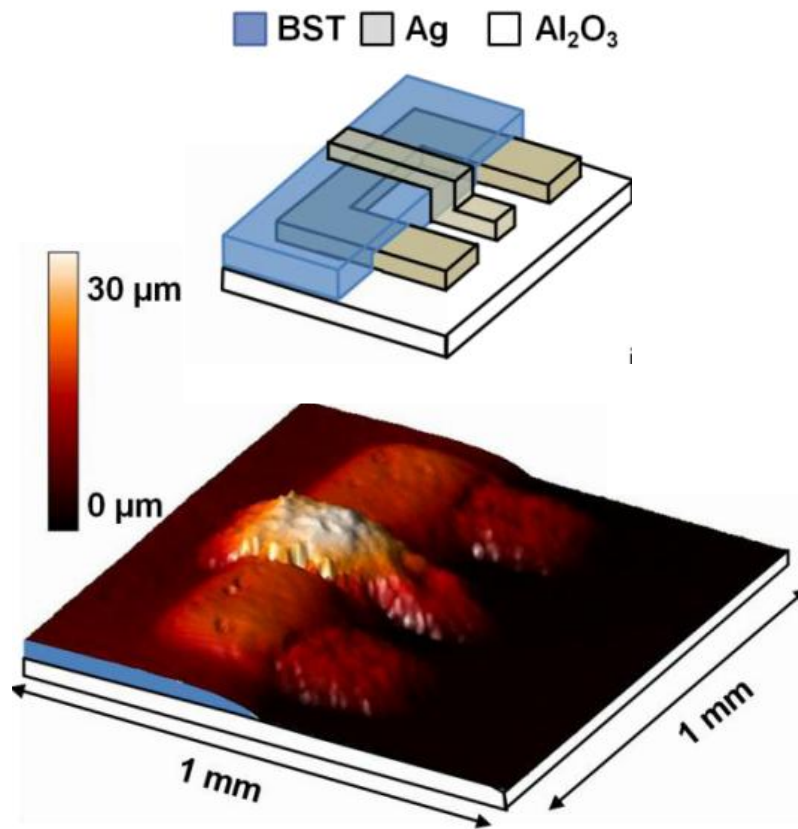


→ decrease of  $\epsilon$ ,  $\tan \delta$ ,  $\tau$  with increasing additive amount

Due to microstructure

- lower grain sizes
- clustering of particles
- higher content amorphous phase
- change in ratio of Ba:Sr

# Fabricated MIM structures (co-fired at 865°C/1h)



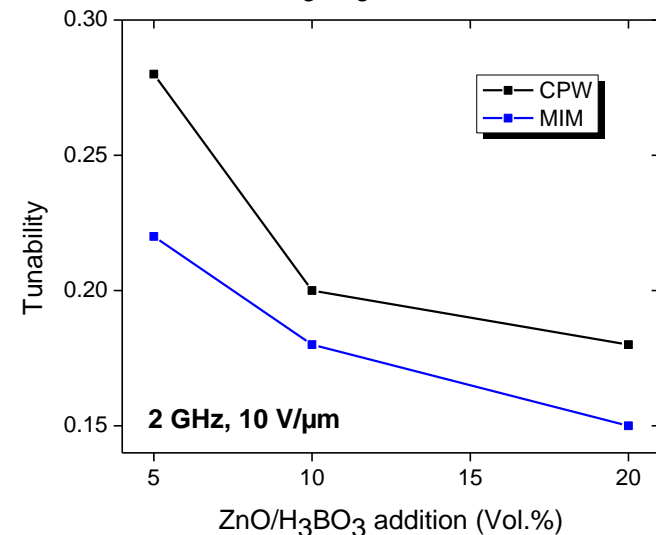
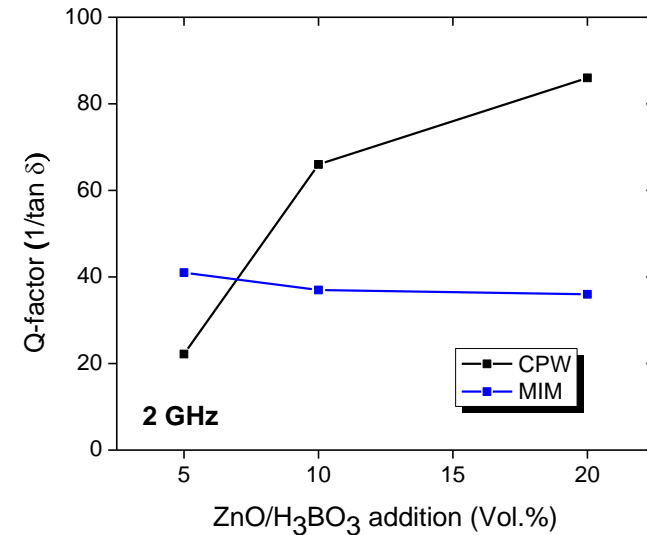
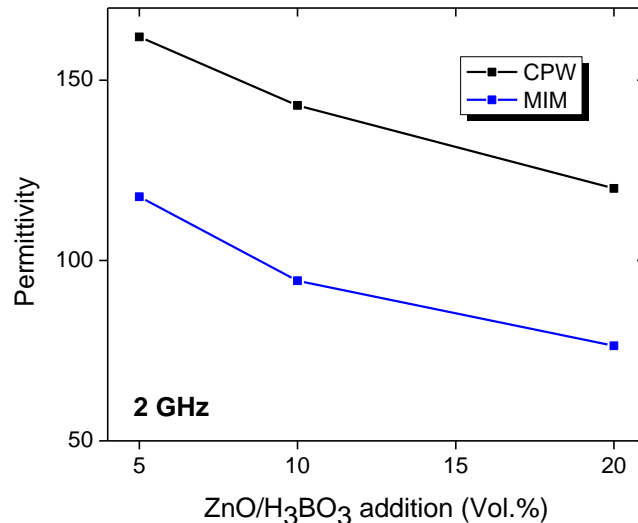
- + good adhesion between layers
- + no reaction (proved by XRD, REM)
- + no infiltration of Ag in porous BST
- + dielectric characterization possible

- quality of silver electrodes (edges, roughness)
- cracks in BST-20ZB thick-film

# Dielectric characterization – CPW vs. MIM (2GHz)

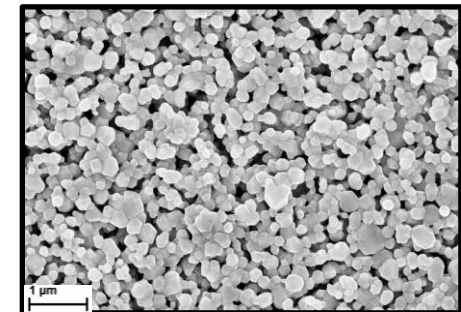
## CPW vs. MIM

- similar trends for permittivity and tunability
- different for Q-values  
(due to loss of rough electrodes for MIM)
- values of tunability for MIM lower than expected (printing quality has to be optimized)



# Summary and Outlook

- **material system BST-ZnO/B<sub>2</sub>O<sub>3</sub>**
  - lowering of sintering temperature achieved
  
- **low temperature sintered BST thick films**
  - dependency of additive amount on the microstructure and phase content
    - grain sizes
    - clustering of particles
    - content of amorphous phase
    - Ba-Sr ratio
  
- **Co-firing of MIM structures**
  - good adhesion and compatibility of multilayers
  
- **Outlook**
  - optimizing printing quality → fully printed RF component
  - usage of CuF-coped BST with ZnO/B<sub>2</sub>O<sub>3</sub>



CuF BST-5ZB ( $\tau = 45\%$ , 80V, 2GHz)

**Thank you for your kind attention!**